

ABSTRACT OF THE DISCLOSURE

An apparatus for stacking a plurality of integrated circuit assemblies includes a connection stack frame for soldering the integrated circuit assemblies. The stack frame has a carved out frame structure or a cavity in the center that has a dimension matching the integrated circuit assemblies. There are solder spots or through holes located on the periphery of the frame structure or cavity. The solder spots may be located on one side or two sides of the stack frame. The one side solder spots are electrically connected to other stack frame surface through leads or conductive through holes. The integrated circuit assemblies are sunken in the frame structure or cavity. The legs of the assemblies are connected to the solder spots. Thus the assemblies are stacked over one another in a layer fashion to form a final assembly package.